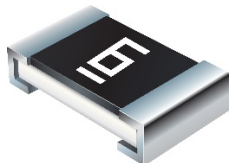


MATERIAL DECLARATION SHEET



Material Number	SF-0603SP-R			
Product Line	SMD Fuses			
Compliance Date	2023/07/13			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	1.647654	Aluminum oxide	1344-28-1	96%	54.48%	56.75%
				Silicon dioxide	14808-60-7	4%	2.27%	
2	Adhesive Layer	Epoxy	0.015932	Epoxy	25068-38-6	82%	0.45%	0.55%
				Trimethylolpropane triglycidyl ether	30499-70-8	18%	0.10%	
3	Fuse Element	Cu	0.376985	Copper	7440-50-8	100%	12.98%	12.98%
4	Over-coating (Black)	Epoxy	0.076679	Epoxy	29690-82-2	100%	2.64%	2.64%
5	Over-coating (White)	Epoxy	0.021409	Epoxy	64742-94-5	50%	0.37%	0.74%
				Titanium dioxide	13463-67-7	50%	0.37%	
6	End Terminal	Ni-Cr Alloy	0.008018	Nickel	7440-02-0	80%	0.22%	0.28%
				Chromium	7440-47-3	20%	0.06%	
7	Plating Cu	Cu	0.493376	Copper	7440-50-8	100%	16.99%	16.99%
8	Plating Ni	Ni	0.131560	Nickel	7440-02-0	100%	4.53%	4.53%
9	Plating Sn	Sn	0.131973	Tin	7440-31-5	100%	4.55%	4.55%
			Total Weight	2.903586				

This Document was updated on: 2023/10/23

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.